



## TE0823 TRM

Revision v.40

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<https://wiki.trenz-electronic.de/display/PD/TE0823+TRM>

# 1 Table of Contents

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1	Table of Contents .....	2
2	Table of Figures .....	4
3	Table of Tables .....	5
4	Overview .....	6
4.1	Key Features .....	6
4.2	Main Components .....	9
4.3	Initial Delivery State .....	9
4.4	Configuration Signals .....	9
5	Signals, Interfaces and Pins .....	11
5.1	Board to Board (B2B) I/Os .....	11
5.2	JTAG Interface .....	11
5.3	MGT Lanes .....	12
5.4	Gigabit Ethernet .....	13
5.5	System Controller CPLD .....	13
5.6	USB Interface .....	14
5.7	I2C Interface .....	15
5.8	MIO Pins .....	15
5.9	Test Points .....	16
6	On-board Peripherals .....	17
6.1	Quad SPI Flash Memory .....	17
6.2	EEPROM .....	18
6.3	LEDs .....	18
6.4	DDR4 SDRAM .....	19
6.5	Gigabyte Ethernet .....	19
6.6	Clock Sources .....	20
6.7	USB2.0 Transceiver .....	20
6.8	eMMC Flash Memory .....	20
6.9	Programmable Clock Generator .....	20
7	Power and Power-On Sequence .....	22
7.1	Power Supply .....	22
7.2	Power Consumption .....	22
7.3	Power Distribution Dependencies .....	22
7.4	Power-On Sequence .....	23
7.5	Power Rails .....	24
7.6	Bank Voltages .....	25

8	Board to Board Connectors.....	27
8.1	Connector Mating height.....	27
8.2	Connector Speed Ratings.....	28
8.3	Current Rating.....	28
8.4	Connector Mechanical Ratings.....	28
9	Technical Specifications.....	29
9.1	Absolute Maximum Ratings.....	29
9.2	Recommended Operating Conditions.....	29
9.3	Physical Dimensions.....	30
10	Currently Offered Variants.....	32
11	Revision History.....	33
11.1	Hardware Revision History.....	33
11.2	Document Change History.....	33
12	Disclaimer.....	34
12.1	Data Privacy.....	34
12.2	Document Warranty.....	34
12.3	Limitation of Liability.....	34
12.4	Copyright Notice.....	34
12.5	Technology Licenses.....	34
12.6	Environmental Protection.....	34
12.7	REACH, RoHS and WEEE.....	35

## 2 Table of Figures

---

Figure 1: TE0823 block diagram .....	8
Figure 2: Power Distribution .....	23
Figure 3: Power Sequency.....	24
Figure 4: Physical Dimension.....	31
Figure 5: Board hardware revision number. ....	33

### 3 Table of Tables

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Table 1: Initial delivery state of programmable devices on the module.....	9
Table 2: Boot process.....	9
Table 3: Reset process. ....	10
Table 4: General PL I/O to B2B connectors information .....	11
Table 5: JTAG pins connection .....	12
Table 6: MGT Lanes connection.....	12
Table 7: GigaBit Ethernet connection .....	13
Table 8: System Controller CPLD special purpose pins .....	14
Table 9: General overview of the USB PHY signals.....	14
Table 10: Address table of the I2C bus slave devices .....	15
Table 11: MIOs pins .....	15
Table 12: Test Points Information .....	16
Table 13: On board peripherals.....	17
Table 14: Quad SPI interface MIOs and pins.....	18
Table 15: I2C EEPROM interface MIOs and pins.....	18
Table 16: I2C address for EEPROM .....	18
Table 17: On-board LEDs .....	18
Table 18: Ethernet PHY to Zynq SoC connections.....	19
Table 19: Osillators .....	20
Table 20: Programmable Clock Generator Inputs and Outputs.....	21
Table 21: Power Consumption .....	22
Table 22: Module power rails.....	25
Table 23: Zynq SoC bank voltages. ....	25
Table 24: Connectors. ....	27
Table 25: Speed rating. ....	28
Table 26: PS absolute maximum ratings .....	29
Table 27: Recommended operating conditions. ....	30
Table 28: Trenz Electronic Shop Overview .....	32
Table 29: Hardware Revision History .....	33
Table 30: Document change history. ....	33

## 4 Overview

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The Trenz Electronic TE0823 (3PIU1FA /3PIU1FL) is an industrial-grade MPSoC module integrating a low power Xilinx Zynq UltraScale+ MPSoC, 1 GByte LPDDR4 SDRAM, 8 GB eMMC chip, 2x 64 MB Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections. The module is equipped with a Lattice Mach XO2 CPLD for system controlling. 3x Robust high-speed connectors provide a large number of inputs and outputs.

The highly integrated modules are smaller than a credit card and are offered in several variants at an affordable price-performance ratio. Modules with a 4 x 5 cm form factor are completely mechanically and largely electrically compatible with each other.

All parts are at least industrial temperature range. The module operating temperature range depends on customer design and cooling solution. Please contact us for options.

Refer to <http://trenz.org/te0823-info> for the current online version of this manual and other available documentation.

### 4.1 Key Features

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- **SoC/FPGA**
  - Package: SFVC784, SFRC784
  - Device: ZU2 ...ZU5, \*
  - Engine: EG, CG, EV, \*
  - Speed: -1, -1L, -2, -2L, 3, \*, \*\*
  - Temperature: I, E, \*, \*\*
- **RAM/Storage**
  - 2x DDR4 SDRAM,
    - Data Width: 32 Bit
    - Size: 16 Gb, \*
    - Speed: 3733 Mbps, \*\*\*
  - 2x QSPI boot Flash in dual parallel mode
    - Data Width: 8 Bit
    - Size: 512 Mb Gb, \*
  - 1x e.MMC Memory
    - Data Width: 8 Bit
    - Size: 32 Gb, \*
  - MAC address serial EEPROM
- **On Board**
  - Lattice MachXO2 CPLD
  - Programmable Clock Generator
  - Hi-speed USB2 ULPI Transceiver
  - 4x LEDs
- **Interface**
  - 1x GB/s serial GMII interface
  - 1x Hi-speed USB2 ULPI transceiver with full OTG support
  - 154 x High Performance (HP) und 96 x High Density (HD) I/Os
  - 78 x PS MIOs
  - 4 x serial PS GTR transceivers
    - PCI Express interface version 2.1 compliant
    - SATA 3.1 specification compliant interface
    - DisplayPort source-only interface with video resolution up to 4k x 2k
    - USB 3.0 specification compliant interface implementing a 5 Gbit/s line rate
- **Power**
  - All power regulators on board
- **Dimension**

- 40 x 50 mm
- **Note**
  - \* depends on assembly version
  - \*\* also non low power assembly options possible
  - \*\*\* depends on used U+ Zynq and DDR4 combination
  - Rugged for shock and high vibration
- **Block Diagram**

# TE0823

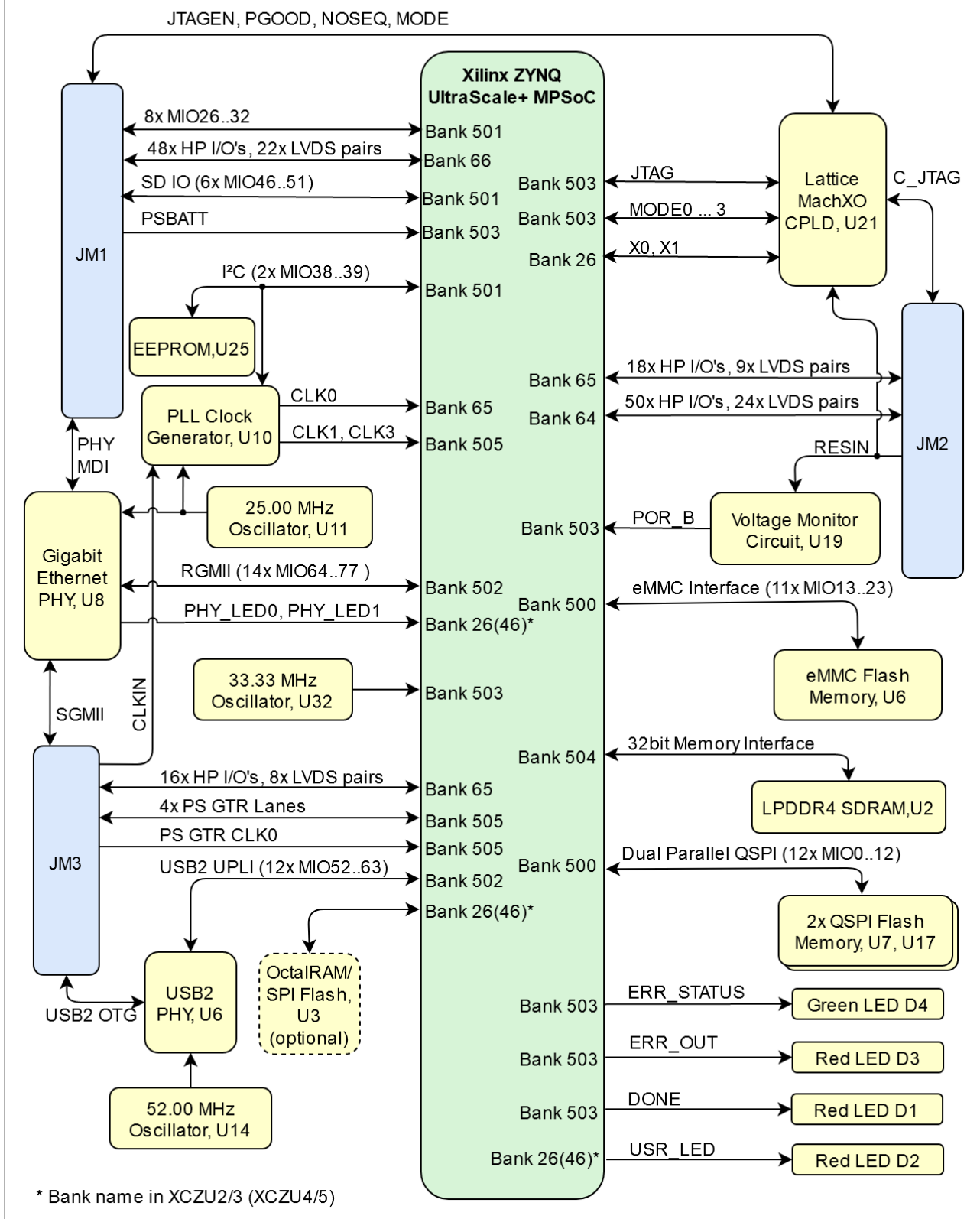


Figure 1: TE0823 block diagram



## 4.2 Main Components

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1. Xilinx Zynq UltraScale+ XCZU3EG, U1
2. Red LED (ERR\_OUT), D3
3. Green User LED, D2
4. Green LED (ERR\_STATUS), D4
5. Red LED (DONE), D1
6. 10/100/1000 Mbps energy efficient ethernet transceiver, U8
7. 8Gb DDR4, U2-U3
8. 512 Mbit QSPI flash memory, U7-U17
9. B2B connector Samtec Razor Beam, JM1
10. B2B connector Samtec Razor Beam, JM3
11. Programmable clock generator, U10
12. USB2.0 Transceiver, U18
13. B2B connector Samtec Razor Beam, JM2
14. 8 GByte eMMC memory, U6
15. Lattice Semiconductor MachXO2 System Controller CPLD, U21

## 4.3 Initial Delivery State

Storage device name	Content	Notes
QSPI Flash Memory	Not programmed	
eMMC Memory	Not programmed	
Programmable Clock Generator	Not programmed	
CPLD (LCMXO2-256HC)	SC0820-02 QSPI Firmware	

**Table 1: Initial delivery state of programmable devices on the module**

## 4.4 Configuration Signals

MODE Signal State	Boot Mode
Low	QSPI

MODE Signal State	Boot Mode
High	SD Card

**Table 2: Boot process.**

Signal	B2B	I/O	Note
RESIN	JM2-18	Input	

**Table 3: Reset process.**

## 5 Signals, Interfaces and Pins

### 5.1 Board to Board (B2B) I/Os

FPGA bank number and number of I/O signals connected to the B2B connector:

FPGA Bank	B2B Connector	I/O Signal Count	Voltage Level	Notes	
24	HD	JM2	24x I/O, 12x LVDS Pairs	Variable	Max voltage 3.3V
25	HD	JM1	24x I/O, 12x LVDS Pairs	Variable	Max voltage 3.3V
26	HD	JM1	24x I/O, 12x LVDS Pairs	Variable	Max voltage 3.3V
44	HD	JM2	24x I/O, 12x LVDS Pairs	Variable	Max voltage 3.3V
65	HP	JM2	18x I/O, 9x LVDS Pairs	Variable	Max voltage 1.8V
65	HP	JM3	16x I/O, 8x LVDS Pairs	Variable	Max voltage 1.8V
505	GTR	JM3	16x I/O, 8x LVDS Pairs	-	4x lanes
505	GTR CLK	JM3	1x Diff Clock	-	
501	MIO	JM1	15 I/O	3.3V	

**Table 4: General PL I/O to B2B connectors information**

### 5.2

#### JTAG Interface

JTAG access to the Xilinx Zynq UltraScale+ is applicable by using Lattice MachXO CPLD through B2B connector JM2.

JTAG Signal	B2B Connector	Notes
TMS	JM2-93	
TDI	JM2-95	
TDO	JM2-97	
TCK	JM2-99	
JTAGEN	JM1-89	Pulled Low: Xilinx Zynq UltraScale+ MPSoC Pulled High: Lattice MachXO CPLD

**Table 5: JTAG pins connection**

### 5.3 MGT Lanes

There are 4x MGT Lanes connected to FPGA Bank 505-GTR.

Lane	Schematic	B2B	Note
0	<ul style="list-style-type: none"> <li>• B505_RX0_P</li> <li>• B505_RX0_N</li> <li>• B505_TX0_P</li> <li>• B505_TX0_N</li> </ul>	<ul style="list-style-type: none"> <li>• JM3-26</li> <li>• JM3-28</li> <li>• JM3-25</li> <li>• JM3-27</li> </ul>	
1	<ul style="list-style-type: none"> <li>• B505_RX1_P</li> <li>• B505_RX1_N</li> <li>• B505_TX1_P</li> <li>• B505_TX1_N</li> </ul>	<ul style="list-style-type: none"> <li>• JM3-20</li> <li>• JM3-22</li> <li>• JM3-19</li> <li>• JM3-21</li> </ul>	
2	<ul style="list-style-type: none"> <li>• B505_RX2_P</li> <li>• B505_RX2_N</li> <li>• B505_TX2_P</li> <li>• B505_TX2_N</li> </ul>	<ul style="list-style-type: none"> <li>• JM3-14</li> <li>• JM3-16</li> <li>• JM3-13</li> <li>• JM3-15</li> </ul>	
3	<ul style="list-style-type: none"> <li>• B505_RX2_P</li> <li>• B505_RX2_N</li> <li>• B505_TX2_P</li> <li>• B505_TX2_N</li> </ul>	<ul style="list-style-type: none"> <li>• JM3-8</li> <li>• JM3-10</li> <li>• JM3-7</li> <li>• JM3-9</li> </ul>	

**Table 6: MGT Lanes connection**

## 5.4 Gigabit Ethernet

On-board Gigabit Ethernet PHY is provided with Marvell Alaska 88E1512 chip. The Ethernet PHY RGMII interface is connected to the Zynq Ethernet0 PS GEM0. I/O voltage is fixed at 1.8V for HSTL signaling. SGMII (SFP copper or fiber) can be used directly with the Ethernet PHY, as the SGMII pins are available on the B2B connector JM3. The reference clock input of the PHY is supplied from an on-board 25MHz oscillator (U11), the 125MHz output clock is left unconnected.

Pin	Schematic	Connected to	Note
MDIP0...3	PHY_MDI0...3	B2B, JM1	
MDC	ETH_MDC	MIO76	
MDIO	ETH_MDIO	MIO77	
S_IN	S_IN	B2B, JM3	
S_OUT	S_OUT	B2B, JM3	
TXD0..3	ETH_TXD0...3	MIO65...68	
TX_CTRL	ETH_TXCTL	MIO69	
TX_CLK	ETH_TXCK	MIO64	
RXD0...3	ETH_RXD0...3	MIO71...74	
RX_CTRL	ETH_RXCTL	MIO75	
RX_CLK	ETH_RXCK	MIO70	
LED0...2	PHY_LED0...2	FPGA Bank 66	
RESETn	ETH_RST	MIO24	

**Table 7: GigaBit Ethernet connection**

## 5.5 System Controller CPLD

Special purpose pins are connected to System Controller CPLD and have following default configuration:

Pin Name	Mode	Function	Default Configuration
EN1	Input	Power Enable	No hard wired function on PCB. When forced low, PGOOD goes low without effect on power management
PGOOD	Output	Power Good	Only indirect used for power status, see CPLD description
NOSEQ	-	-	No used for Power sequencing, see CPLD description
RESIN	Input	Reset	Active low reset, gated to POR_B
JTAGEN	Input	JTAG Select	Low for normal operation, high for CPLD JTAG access

**Table 8: System Controller CPLD special purpose pins**

## 5.6 USB Interface

USB PHY is provided by Microchip USB3320. The ULPI interface is connected to the Zynq PS USB0. I/O voltage is fixed at 1.8V. Reference clock input for the USB PHY is supplied by the on-board 52.00 MHz oscillator (U14).

PHY Pin	ZYNQ Pin	B2B Name	Notes
ULPI	MIO52..63	-	Zynq USB0 MIO pins are connected to the USB PHY.
REFCLK	-	-	52.000000 MHz from on-board oscillator (U14).
REFSEL[0..2]	-	-	Reference clock frequency select, all set to GND selects 52.000000 MHz.
RESETB	MIO25	-	Active low reset.
CLKOUT	MIO52	-	Connected to 1.8V, selects reference clock operation mode.
DP, DM	-	OTG_D_P, OTG_D_N	USB data lines routed to B2B connector JM3 pins 47 and 49.
CPEN	-	VBUS_V_EN	External USB power switch active high enable signal, routed to JM3 pin 17.

PHY Pin	ZYNQ Pin	B2B Name	Notes
VBUS	-	USB_VBUS	Connect to USB VBUS via a series of resistors, see reference schematics, routed to JM3 pin 55.
ID	-	OTG_ID	For an A-device connect to ground, for a B-device left floating. routed from JM3 pin 23.

**Table 9: General overview of the USB PHY signals**

## 5.7 I2C Interface

On-board I<sup>2</sup>C devices are connected to MIO38 (SCL) and MIO39 (SDA) which are configured as I<sup>2</sup>C0 by default. Addresses for on-board I<sup>2</sup>C slave devices are listed in the table below:

I2C Device	I2C Address	Notes
Si5338A PLL	0x70	-
EEPROM	0x50	-

**Table 10: Address table of the I2C bus slave devices**

## 5.8 MIO Pins

MIO Pin	Connected to	B2B	Notes
0...5	QSPI Flash, U7	-	SPI Flash
7...12	QSPI Flash, U17	-	SPI Flash
13...23	eMMC, U6		
24	ETH Transceiver, U8	-	ETH_RST
25	USB2.0 Transceiver, U18	-	OTG_RST
26...33	User MIO	JM1	
34...37	N.C	-	N.C
38...39	EEPROM, U25	-	I2C_SDA/SCL

MIO Pin	Connected to	B2B	Notes
40...45	N.C		N.C
46...51	SD Card	JM1	
52...63	USB2.0 Transceiver, U18	-	
63...77	Ethernet Transceiver, U8	-	

**Table 11: MIOs pins**

## 5.9 Test Points

Test Point	Signal	Connected to	Notes
1	PS_LP0V85	Regulator, U12	
2	SRST_B	FPGA Bank 503, U1H	PSCONFIG
3	PS_AVCC	Regulator, U9	
4	+1.1V_LPDDR4	Regulator, U15	
5	PS_AVTT	Regulator, U13	
6	-	-	
7	PS_FP0V85	Regulator, U26	
8	PS_LP0V85	Voltage Regulator, U12	
9	POR_B	Voltage Regulator, U19	
10	PS_PLL	Voltage Regulator, U23	
11	PL_VCCINT	Voltage Regulator, U5	
12...15	-	-	
16	PL_VCU	Voltage Regulator, U24	

**Table 12: Test Points Information**



## 6 On-board Peripherals

Chip/Interface	Designator	Notes
QSPI Flash <sup>1</sup>	U7, U17	
EEPROM <sup>2</sup>	U25	
DDR4 SDRAM <sup>3</sup>	U2,U3	
GigaBit Ethernet <sup>4</sup>	U8	
USB2.0 Transceiver <sup>5</sup>	U18	
eMMC Memory <sup>6</sup>	U6	
Oscillators <sup>7</sup>	U32, U14, U11	
Programmable Clock Generator <sup>8</sup>	U25	
CPLD <sup>9</sup>	U21	
LEDs <sup>10</sup>	D1...3	

**Table 13: On board peripherals**

### 6.1 Quad SPI Flash Memory

The TE0821 is equipped with dual Flash Memory, U7, U17. Two quad SPI compatible serial bus flash memory chips are provided for FPGA configuration file and data storage. After configuration completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency.

1 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-QuadSPIFlashMemory>

2 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-EEPROM>

3 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-DDR4SDRAM>

4 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-GigabitEthernet>

5 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-USB2.0Transceiver>

6 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-eMMCMemory>

7 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-ClockSources>

8 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-ProgrammableClockGenerator>

9 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-SystemControllerCPLD>

10 <https://wiki.trenz-electronic.de/display/DRAFT/TE0821+TRM#TE0821TRM-LEDs>

Pin	Schematic		Notes
	QSPI, U7	QSPI, U17	
nCS	MIO5	MIO7	
CLK	MIO0	MIO12	
DI/IO0	MIO4	MIO8	
DO/IO1	MIO1	MIO9	
nHOLD/IO3	MIO3	MIO11	
WP/IO2	MIO2	MIO10	

**Table 14: Quad SPI interface MIOs and pins**

## 6.2 EEPROM

There is a 2Kb EEPROM provided on the module TE0821.

MIO Pin	Schematic	U?? Pin	Notes
MIO39	I2C_SDA	SDA	
MIO38	I2C_SCL	SCL	

**Table 15: I2C EEPROM interface MIOs and pins**

MIO Pin	I2C Address	Designator	Notes
MIO38-MIO39	0x50	U25	

**Table 16: I2C address for EEPROM**

## 6.3 LEDs

Designator	Color	Connected to	Active Level	Note
D1	Red	DONE	Low	
D2	Green	USR_LED	High	
D3	Red	ERR_OUT	High	

Designator	Color	Connected to	Active Level	Note
D4	Green	ERR_STATUS	High	

**Table 17: On-board LEDs**

## 6.4 DDR4 SDRAM

The TE0823 SoM has a 1 GB volatile LPDDR4 SDRAM IC for storing user application code and data.

- Part number: IS43LQ32256A
- Supply voltage: 1.7V ~ 1.95V
- Speed: 3200 Mbps
- Temperature: -40 ~ 95 °C

## 6.5 Gigabyte Ethernet

On-board Gigabit Ethernet PHY (U8) is provided with Marvell Alaska 88E1512 IC (U8). The Ethernet PHY RGMII interface is connected to the ZynqMP Ethernet3 PS GEM3. I/O voltage is fixed at 1.8V for HSTL signaling. The reference clock input of the PHY is supplied from an on-board 25.00 MHz oscillator (U11).

U8 Pin	Schematic	Connected to	Note
MDIP0...3	PHY_MDI0...3	B2B, JM1	
MDC	ETH_MDC	MIO76	
MDIO	ETH_MDIO	MIO77	
S_IN	S_IN	B2B, JM3	
S_OUT	S_OUT	B2B, JM3	
TXD0..3	ETH_TXD0...3	MIO65...68	
TX_CTRL	ETH_TXCTL	MIO69	
TX_CLK	ETH_TXCK	MIO64	
RXD0...3	ETH_RXD0...3	MIO71...74	
RX_CTRL	ETH_RXCTL	MIO75	
RX_CLK	ETH_RXCK	MIO70	
LED0...2	PHY_LED0...2	FPGA Bank 66	

U8 Pin	Schematic	Connected to	Note
RESETn	ETH_RST	MIO24	

**Table 18: Ethernet PHY to Zynq SoC connections**

## 6.6 Clock Sources

Designator	Description	Frequency	Note
U11	MEMS Oscillator	25 MHz	
U14	MEMS Oscillator	52 MHz	
U32	MEMS Oscillator	80 MHz	

**Table 19: Osillators**

## 6.7 USB2.0 Transceiver

Hi-speed USB ULPI PHY (U18) is provided with USB3320 from Microchip. The ULPI interface is connected to the Zynq PS USB0 via MIO52..63, bank 502. The I/O voltage is fixed at 1.8V and PHY reference clock input is supplied from the on-board 52.00 MHz oscillator (U14).

## 6.8 eMMC Flash Memory

eMMC Flash memory device(U6) is connected to the ZynqMP PS MIO bank 500 pins MIO13..MIO23. eMMC chips IS21ES08G-JCLI (FLASH - NAND Speicher-IC (64 Gb x 1) MMC ) is used.

## 6.9 Programmable Clock Generator

There is a Silicon Labs I<sup>2</sup>C programmable clock generator Si5338A (U10) chip on the module. It's output frequencies can be programmed using the I<sup>2</sup>C bus address 0x70 or 0x71. Default address is 0x70, IN4/I2C\_LSB pin must be set to high for address 0x71.

A 25.00 MHz oscillator is connected to the pin IN3 and is used to generate the output clocks. The oscillator has its output enable pin permanently connected to 1.8V power rail, thus making output frequency available as soon as 1.8V is present. Three of the Si5338 clock outputs are connected to the FPGA. One is connected to a logic bank and the other two are connected to the GTR banks.

Once running, the frequency and other parameters can be changed by programming the device using the I<sup>2</sup>C bus connected between the FPGA (master) and clock generator (slave). For this, proper I<sup>2</sup>C bus logic has to be implemented in FPGA.

U25 Pin	Signal	Connected to	Direction	Note
IN0..1	CLK_IN	JM3	IN	
IN2	CLK_25M	Oscillator, U11	IN	
SCL	I2C_SCL	EEPROM,U25	INOUT	
SDA	I2C_SDA	EEPROM,U25	INOUT	
CLK0	CLK0	JM3	OUT	
CLK1	B505_CLK3	FPGA Bank 505	IN	
CLK2	B505_CLK1	FPGA Bank 505	IN	
CLK3	CLK3_N		IN	

**Table 20: Programmable Clock Generator Inputs and Outputs**

## 7 Power and Power-On Sequence

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### 7.1 Power Supply

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Power supply with minimum current capability of 2.5 A for system startup is recommended.

### 7.2 Power Consumption

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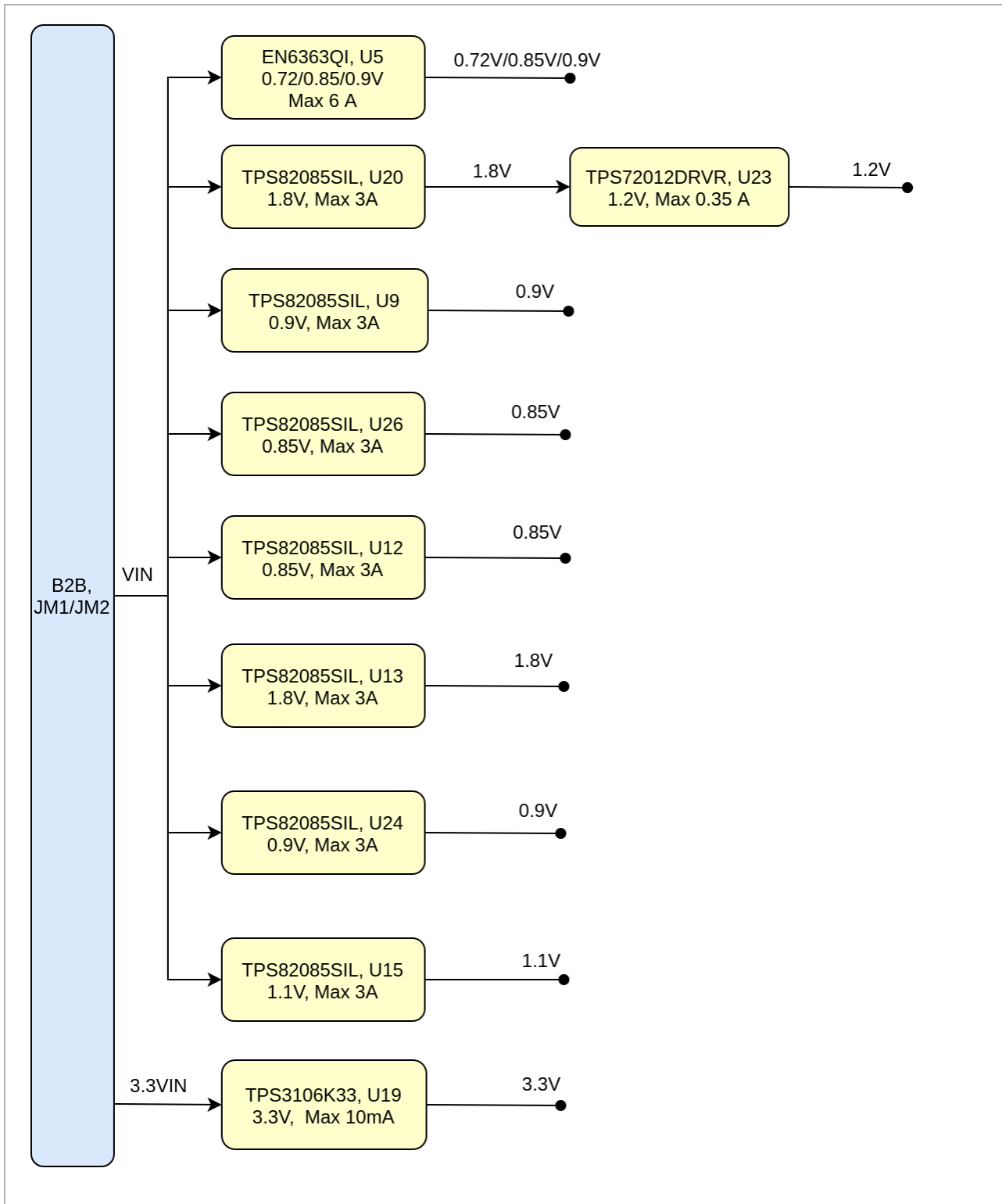
Power Input Pin	Typical Current
VIN	TBD*

**Table 21: Power Consumption**

\* TBD - To Be Determined

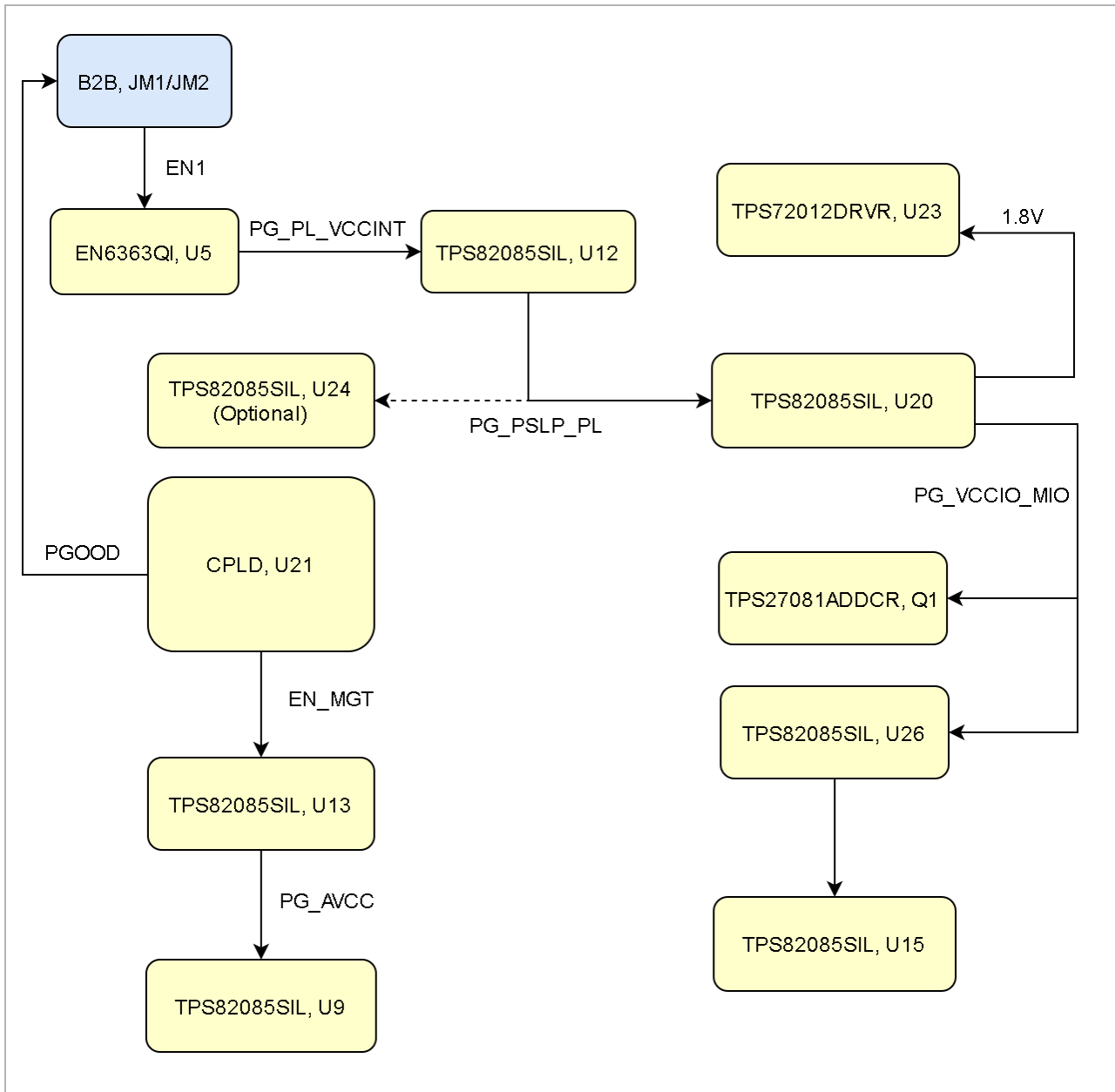
### 7.3 Power Distribution Dependencies

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**Figure 2: Power Distribution**

## 7.4 Power-On Sequence



**Figure 3: Power Sequency**

## 7.5 Power Rails



Power Rail Name	B2B Connector	B2B Connector	B2B Connector	Direction	Notes
	JM1 Pin	JM2 Pin	JM3 Pin		
VIN	1, 3, 5	2, 4, 6, 8	Input	Supply voltage from the carrier board	
3.3V	-	10, 12	Output	Internal 3.3V voltage level	
3.3VIN	13, 15	-	Input	Supply voltage from the carrier board	
1.8V	39	-	Output	Internal 1.8V voltage level	
JTAG VREF	-	91	Output	JTAG reference voltage. Attention: Net name on schematic is "3.3VIN"	
VCCO_64	-	7, 9	Input	High performance I/O bank voltage	
VCCO_65	-	5	Input	High performance I/O bank voltage	
VCCO_66	9, 11	-	Input	High performance I/O bank voltage	

**Table 22: Module power rails.**

## 7.6 Bank Voltages

Bank	Schematic Name	Voltage	Notes
24 HD	VCCO_HD24_24	Variable	Max voltage 3.3V
25 HD		Variable	Max voltage 3.3V
26 HD	VCCO_HD25_26	Variable	Max voltage 3.3V
44 HD	VCCO_HD24_44	Variable	Max voltage 3.3V
65 HP	VCCO_65	Variable	Max voltage 1.8V

Bank	Schematic Name	Voltage	Notes
66 HP	VCCO_66	1.8V	
500 PSMIO	VCCO_PSIO0_500	1.8V	
501 PSMIO	VCCO_PSIO1_501	3.3V	
502 PSMIO	VCCO_PSIO2_502	1.8V	
503 PSCONFIG	VCCO_PSIO3_503	1.8V	
504 PSDDR	DDR_1V2	1.2V	

**Table 23: Zynq SoC bank voltages.**

## 8

# Board to Board Connectors

⚠ These connectors are hermaphroditic. Odd pin numbers on the module are connected to even pin numbers on the baseboard and vice versa.

4 x 5 modules use two or three [Samtec Razor Beam LSHM connectors](#)<sup>11</sup> on the bottom side.

- 2 x REF-189016-02 (compatible to LSHM-150-04.0-L-DV-A-S-K-TR), (100 pins, "50" per row)
- 1 x REF-189017-02 (compatible to LSHM-130-04.0-L-DV-A-S-K-TR), (60 pins, "30" per row) (depending on module)

## 8.1 Connector Mating height

When using the same type on baseboard, the mating height is 8mm. Other mating heights are possible by using connectors with a different height

Order number	Connector on baseboard	compatible to	Mating height
23836	REF-189016-01	LSHM-150-02.5-L-DV-A-S-K-TR	6.5 mm
	LSHM-150-03.0-L-DV-A-S-K-TR	LSHM-150-03.0-L-DV-A-S-K-TR	7.0 mm
23838	REF-189016-02	LSHM-150-04.0-L-DV-A-S-K-TR	8.0 mm
	LSHM-150-06.0-L-DV-A-S-K-TR	LSHM-150-06.0-L-DV-A-S-K-TR	10.0mm
26125	REF-189017-01	LSHM-130-02.5-L-DV-A-S-K-TR	6.5 mm
	LSHM-130-03.0-L-DV-A-S-K-TR	LSHM-130-03.0-L-DV-A-S-K-TR	7.0 mm
24903	REF-189017-02	LSHM-130-04.0-L-DV-A-S-K-TR	8.0 mm
	LSHM-130-06.0-L-DV-A-S-K-TR	LSHM-130-06.0-L-DV-A-S-K-TR	10.0mm

**Table 24: Connectors.**

<sup>11</sup> <https://www.samtec.com/technical-specifications/Default.aspx?SeriesMaster=LSHM>

The module can be manufactured using other connectors upon request.

## 8.2 Connector Speed Ratings

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The LSHM connector speed rating depends on the stacking height; please see the following table:

Stacking height	Speed rating
12 mm, Single-Ended	7.5 GHz / 15 Gbps
12 mm, Differential	6.5 GHz / 13 Gbps
5 mm, Single-Ended	11.5 GHz / 23 Gbps
5 mm, Differential	7.0 GHz / 14 Gbps

**Table 25: Speed rating.**

## 8.3 Current Rating

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Current rating of Samtec Razor Beam™ LSHM B2B connectors is 2.0A per pin (2 adjacent pins powered).

## 8.4 Connector Mechanical Ratings

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- Shock: 100G, 6 ms Sine
- Vibration: 7.5G random, 2 hours per axis, 3 axes total

## 9 Technical Specifications

### 9.1 Absolute Maximum Ratings

Symbols	Description	Min	Max	Unit
VIN supply voltage	-0.3	7	V	See EN6347QI and TPS82085SIL datasheets
3.3VIN supply voltage	-0.1	3.630	V	Xilinx DS925 and TPS27082L datasheet
PS I/O supply voltage, VCCO_PSIO	-0.5	3.630	V	Xilinx document DS925
PS I/O input voltage	-0.5	VCCO_PSI O + 0.55	V	Xilinx document DS925
HP I/O bank supply voltage, VCCO	-0.5	2.0	V	Xilinx document DS925
HP I/O bank input voltage	-0.55	VCCO + 0.55	V	Xilinx document DS925
PS GTR reference clocks absolute input voltage	-0.5	1.1	V	Xilinx document DS925
PS GTR absolute input voltage	-0.5	1.1	V	Xilinx document DS925
Voltage on SC CPLD pins	-0.5	3.75	V	Lattice Semiconductor MachXO2 datasheet
Storage temperature	-40	+85	°C	See eMMC datasheet

**Table 26: PS absolute maximum ratings**

### 9.2 Recommended Operating Conditions

Operating temperature range depends also on customer design and cooling solution. Please contact us for options.

Parameter	Min	Max	Units	Reference Document
VIN supply voltage	3.3	6	V	See TPS82085S datasheet
3.3VIN supply voltage	3.3	3.465	V	See LCMXO2-256HC, Xilinx DS925 datasheet
PS I/O supply voltage, VCCO_PSIO	1.710	3.465	V	Xilinx document DS925
PS I/O input voltage	-0.20	VCCO_PSI O + 0.20	V	Xilinx document DS925
HP I/O banks supply voltage, VCCO	0.950	1.9	V	Xilinx document DS925
HP I/O banks input voltage	-0.20	VCCO + 0.20	V	Xilinx document DS925
Voltage on SC CPLD pins	-0.3	3.6	V	Lattice Semiconductor MachXO2 datasheet
Operating Temperature Range	0	85	°C	Xilinx document DS925, extended grade Zynq temperature range

**Table 27: Recommended operating conditions.**

## 9.3 Physical Dimensions

- Module size: 40 mm × 50 mm. Please download the assembly diagram for exact numbers.
- Mating height with standard connectors: 8 mm.

PCB thickness: 1.7 mm.

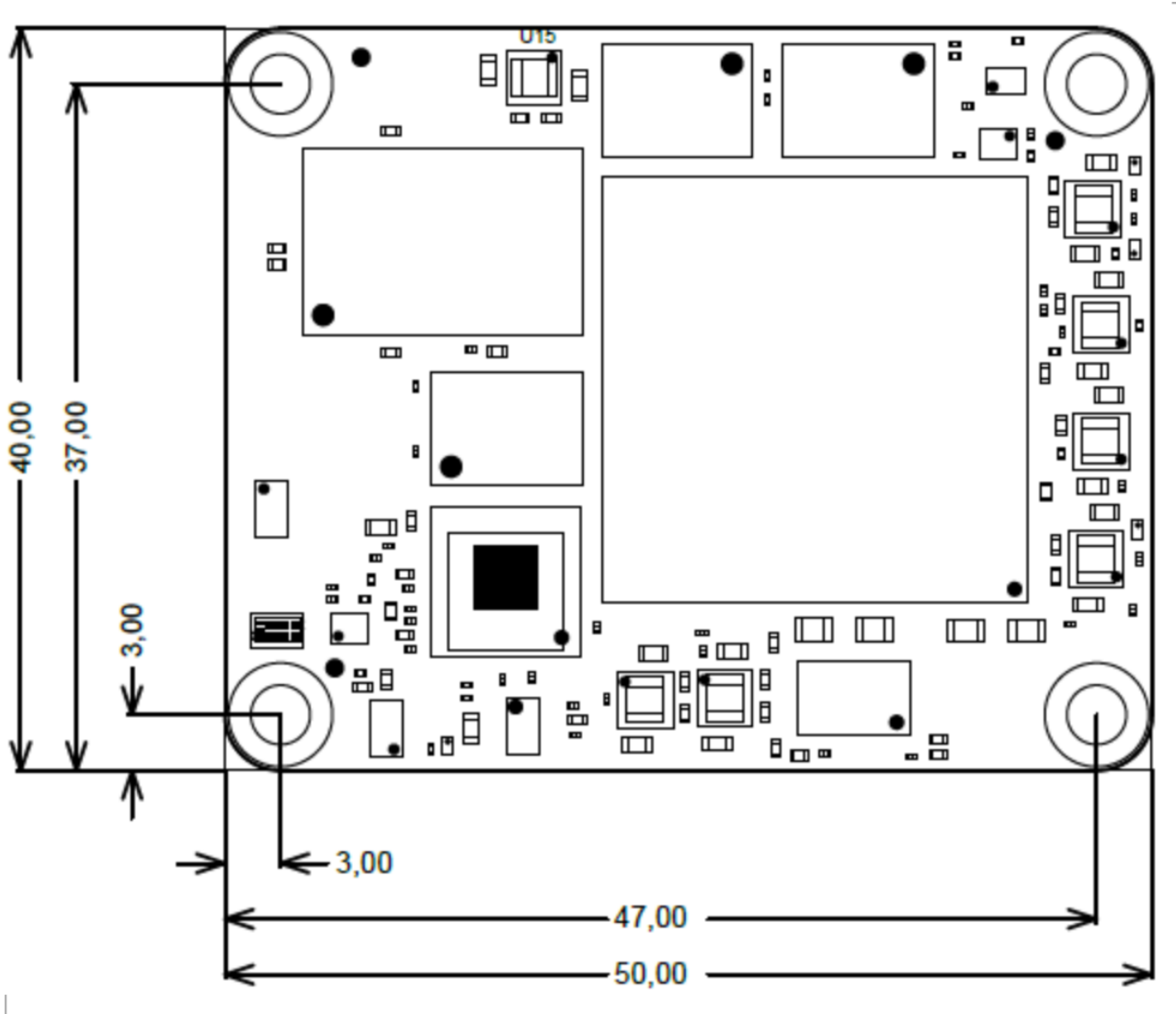


Figure 4: Physical Dimension

## 10 Currently Offered Variants

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<b>Trenz shop TE0823 overview page</b>	
<a href="#">English page(see page 6)</a>	<a href="#">German page<sup>12</sup></a>

**Table 28: Trenz Electronic Shop Overview**

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<sup>12</sup> <https://shop.trenz-electronic.de/de/search?sSearch=TE0823>



## 11 Revision History

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### 11.1 Hardware Revision History

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Date	Revision	Changes	Documentation Link
2018-09-25	REV01	Initial Release	REV01

**Table 29: Hardware Revision History**

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.



**Figure 5: Board hardware revision number.**

### 11.2 Document Change History

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Date	Revision	Contributor	Description
 2020-11-02	v.40(see page 6)	<a href="#">Pedram Babakhani</a> <sup>13</sup>	<ul style="list-style-type: none"> <li>Initial Release</li> </ul>
--	all	<a href="#">Pedram Babakhani</a> <sup>14</sup> , <a href="#">John Hartfiel</a> <sup>15</sup> , <a href="#">Vadim Yunitski</a> <sup>16</sup>	<ul style="list-style-type: none"> <li>--</li> </ul>

**Table 30: Document change history.**

<sup>13</sup> <https://wiki.trenz-electronic.de/display/~P.Babakhani>

<sup>14</sup> <https://wiki.trenz-electronic.de/display/~P.Babakhani>

<sup>15</sup> <https://wiki.trenz-electronic.de/display/~j.hartfiel>

<sup>16</sup> <https://wiki.trenz-electronic.de/display/~v.yunitzki>

## 12 Disclaimer

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### 12.1 Data Privacy

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Please also note our data protection declaration at <https://www.trenz-electronic.de/en/Data-protection-Privacy>

### 12.2 Document Warranty

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## 12.7 REACH, RoHS and WEEE

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### REACH

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of REACH<sup>17</sup>. The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no SVHC (Substances of Very High Concern) on the Candidate List<sup>18</sup> are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA)<sup>19</sup>.

### RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

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Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

 2019-06-07

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<sup>17</sup> <http://guidance.echa.europa.eu/>

<sup>18</sup> <https://echa.europa.eu/candidate-list-table>

<sup>19</sup> <http://www.echa.europa.eu/>